

*A1*

---

## CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation-in-part of U.S. Application No. 09/651,779, titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to U.S. Application No. 09/888,084 (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material From a Microelectronic Substrate," filed June 21, 2001, and U.S. Application No. 09/888,002 (attorney docket number 108298515US3), titled "Methods and Apparatus for Electrically and/or Chemically-Mechanically Removing Conductive Material From a Microelectronic Substrate," filed June 21, 2001. All of the U.S. Patent Applications listed above are incorporated herein by reference.

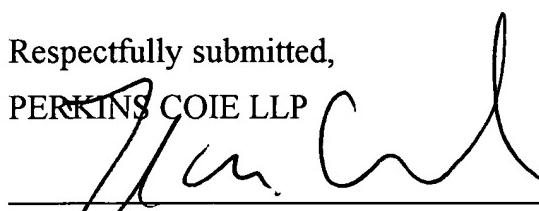
---

## REMARKS

Applicants respectfully request consideration of the application in view of this preliminary amendment. The enclosed Declaration reflects the priority claim, as corrected in this Preliminary Amendment. If the Examiner has any questions or matters that can be expediently handled by telephone, he or she is encouraged to contact Mr. Wechkin, attorney for the Applicants.

Respectfully submitted,

PERKINS COIE LLP

  
John M. Wechkin  
Registration No. 42,216

---

JMW:ri

PERKINS COIE LLP  
1201 Third Avenue, Suite 4800  
Seattle, Washington 98101-3009  
(206) 583-8888  
FAX: (206) 583-8500